

INITIAL PRODUCT/PROCESS CHANGE NOTIFICATION Generic Copy

08-Feb-2006

SUBJECT: ON Semiconductor Initial Product/Process Change Notification #15335

TITLE: Initial Notification of Qualification of OSPI for Assembly/Test of 8/14/16 Lead SOIC Narrow Packages

EFFECTIVE DATE: 08-Jun-2006

AFFECTED CHANGE CATEGORY: ON Semiconductor Assembly & Test Site

AFFECTED PRODUCT DIVISION: Analog Power Management

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact Sales Office or Alan Garlington rpr180 @onsemi.com>

NOTIFICATION TYPE:

Initial Product/Process Change Notification (IPCN)

First change notification sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.

The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN).

This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 60 days prior to implementation of the change.

DESCRIPTION AND PURPOSE:

Initial Process Change Notice to notify customers of the capacity expansion of the ON Semiconductor assembly/test location at Carmona, Philippines (OSPI) for 8/14/16 lead narrow SOIC packages. The devices listed on this IPCN have historically been assembled/tested at the ASE assembly/test facility located in Chung Li, Taiwan. At the expiration of this Initial PCN and subsequent Final PCN, these devices may be processed at either location. The ON Semiconductor facility at Carmona, Philippines is fully qualified and has been producing the SOIC narrow body products for many years. The capacity expansion will involve duplication of the existing equipment set currently in production.

QUALIFICATION PLAN:

Standard equipment set certification procedures will be followed prior to being placed into production.

Reliability qualification is through qualification by similarity with existing production.

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AFFECTED DEVICE LIST:

PART

MC1403D

MC1403DR2

MC26LS30D

MC26LS30DR2

MC33232D

MC33232DG

MC33232DR2

MC33232DR2G

MC33260DG

MC33260DR2

MC33260DR2G

MC33364D

MC33364D1

MC33364D1R2

MC33364D2

MC33364D2R2

MC33364DG

MC33364DR2

MC33364DR2G

MC33368D

MC33368DG

MC33368DR2

MC33368DR2G

MC33567D-1R2G

NCP1603D100R2

SC111018DR2

SC111021BVD1R2

SC111400ADR2

SC33262DR2

SC33262DR2G

SC74808DR2

SC78L12ABDR2

SC79137BDR2

SC79140DR2

SC79155DR2

SC79156DR2

SC79157DR2

SC79173DR2

SC79176DNLR2

SC79181DR2

SCY99011DR2

TY40470R2 UAA2016AD

UAA2016D

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